

Electronic Patent Application Fee Transmittal				
Application Number:	10620346			
Filing Date:	17-Jul-2003			
Title of Invention:	Copper paste, wiring board using the same, and production method of wiring board			
First Named Inventor/Applicant Name:	Hiroshi Sumi			
Filer:	Abraham Jacob Rosner/Kelley Liphard			
Attorney Docket Number:	Q76616			
Filed as Large Entity				
Utility under 35 USC 111(a) Filing Fees				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				
Post-Allowance-and-Post-Issuance:				
Extension-of-Time:				
Extension - 2 months with \$0 paid	1252	1	460	460

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
Request for continued examination	1801	1	810	810
Total in USD (\$)				1270